SDAS096C - JANUARY 1986 - REVISED JANUARY 1995

- Functionally Equivalent to AMD's AM29863
- Power-Up High-Impedance State
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs

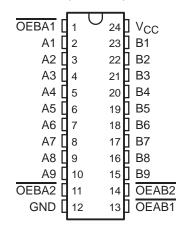
description

This 9-bit transceiver is designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB1, OEAB2, OEBA1, and OEBA2) inputs.

The SN74ALS29863 is characterized for operation from 0°C to 70°C.

DW OR NT PACKAGE (TOP VIEW)



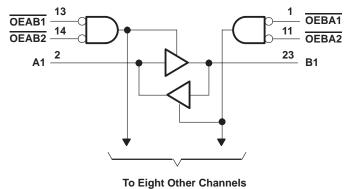
FUNCTION TABLE

	INP	ODEDATION		
OEAB1	OEAB2	OEBA1	OEBA2	OPERATION
L	L	L	L	Latch A and B
L	L	Н	Χ	A 40 D
L	L	Χ	Н	A to B
Н	Χ	L	L	D (- A
Х	Н	L	L	B to A
Н	Χ	Н	Χ	
Н	Χ	Χ	Н	Isolation
Х	Н	Χ	Н	isolation
Х	Н	Н	Χ	

logic symbol†

& OEBA1 EN1 11 OEBA2 13 OEAB1 EN2 14 OEAB2 23 В1 **▽ 1** ◁ 2 ▽ 22 B2 Α2 21 4 А3 В3 5 20 **B**4 Α4 19 Α5 **B5** 7 18 **B6** A6 17 Α7 **B7** 16 **A8 B8** 15 10 В9 A9

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	 7 V
Input voltage, V _I (all inputs and I/O ports)	 5.5 V
Operating free-air temperature range, TA	 0°C to 70°C
Storage temperature range	 5°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V _{IL}	Low-level input voltage			8.0	V
ІОН	High-level output current			-24	mA
lOL	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

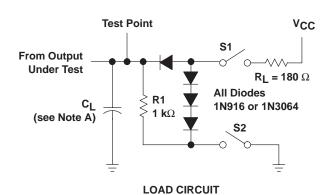
	PARAMETER	NDITIONS	MIN	TYP†	MAX	UNIT	
٧ıĸ		$V_{CC} = 4.75 V$,	$I_{I} = -18 \text{ mA}$			-1.2	V
.,		V 475 V	$I_{OH} = -15 \text{ mA}$	2.4			.,
VOH		$V_{CC} = 4.75 \text{ V}$	$I_{OH} = -24 \text{ mA}$	2			V
VOL	$V_{CC} = 4.75 V$,		$I_{OL} = 48 \text{ mA}$		0.35	0.5	V
II		$V_{CC} = 5.25 V$,	V _I = 5.5 V			0.1	mA
	Control inputs	V 5.05.V	V 07V			20	
lН	A or B ports‡	$V_{CC} = 5.25 \text{ V},$	$5 \text{ V}, \qquad \text{V}_{\text{I}} = 2.7 \text{ V}$			20	μΑ
	Control inputs	., 5.05.1/	V 0.43V			-0.1	
ΊL	A or B ports‡	$V_{CC} = 5.25 \text{ V},$	V _I = 0.4 V			-0.1	mA
IOS§		$V_{CC} = 5.25 \text{ V},$	V _O = 0	-75		-250	mA
ICC		$V_{CC} = 5.25 \text{ V}$			40	65	mA

switching characteristics (see Figure 1)

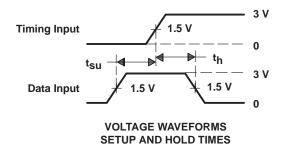
DARAMETER	FROM	то	TEGT COMPITIONS	V _{CC} = 4.75 \			
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT	
t _{PLH}	A - : : D	D A	0 000 = 5		15		
t _{PHL}	A or B	B or A	C _L = 300 pF		15	ns	
^t PLH	A D	D A	0 50 - 5		8		
t _{PHL}	A or B	B or A	C _L = 50 pF		8	ns	
^t PZH	OFAD - OFDA	A - :: D	0 000 = 5		20		
tpZL	OEAB or OEBA	A or B	C _L = 300 pF		23	ns	
^t PZH	<u> </u>	. 5	0 50 5		15		
t _{PZL}	OEAB or OEBA	A or B	$C_L = 50 pF$		15	ns	
^t PHZ	OEAB or OEBA	A - : : D	0 50 - 5		17		
tpLZ	OEAB or OEBA	A or B	$C_L = 50 pF$		12	ns	
^t PHZ	OEAB or OEBA	A or B	C _L = 5 pF		9	20	
t _{PLZ}	OEAD UI OEBA	OEAD OF OEDA A OF B			9	ns	

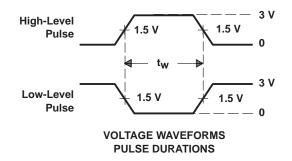
[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current. § Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

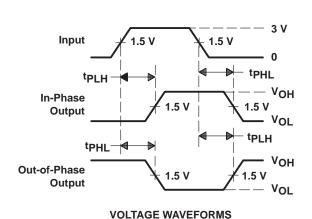
PARAMETER MEASUREMENT INFORMATION

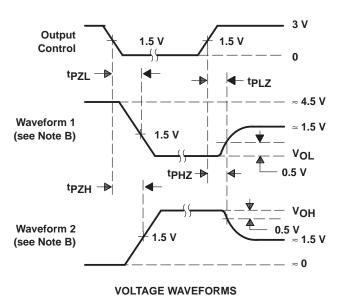


SWITCH POSITION TABLE						
TEST	S1	S 2				
tPLH tPHL tPZH tPZL tPHZ tPHZ	Closed Closed Open Closed Closed Closed	Closed Closed Closed Open Closed Closed				









ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

tance

NOTES: A. C_L includes probe and jig capacitance.

PROPAGATION DELAY TIMES

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms







com 18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS29863DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS29863NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS29863DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1





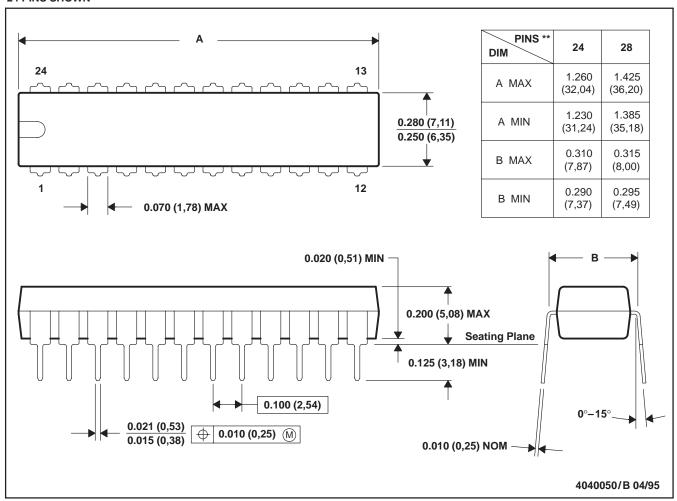
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS29863DWR	SOIC	DW	24	2000	346.0	346.0	41.0

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

DW (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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